

RECEIVED  
CENTRAL FAX CENTER

MAR 13 2008

Patent

Customer No. 31561  
Docket No. 10544-US-PA  
Application No.: 10/709,179

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chang et al.  
 Application No. : 10/709,179  
 Filed : April 19, 2004  
 For : STACK-TYPE MULTI-CHIP PACKAGE AND METHOD OF  
 FABRICATING BUMPS ON THE BACKSIDE OF A CHIP  
 Examiner : Ha, Nathan W.  
 Art Unit : 2814

TRANSMITTAL LETTER

+1-571-273-8300

(Via fax: 2+ 7 pages)

United States Patent and Trademark Office  
 Customer Service Window  
 Mail Stop Amendment  
 Randolph Building  
 401 Dulany Street  
 Alexandria, VA 22314

Dear Sir,

In response to the Office Action dated December 13, 2007, please find the relevant paper in response to paper No. 20071209 as follows:

- Amendment and Response to Office Action in (7) pages.

The Applicant is NOT entitled to a status as a Small Entity; accordingly, please charge the following fees to the Deposit Account No.: 50-2620 (Order No.:10544-US-PA).

Fees are calculated as follows:

<input type="checkbox"/> Extra Claims Fee :						
	NUMBER FILED	CLAIMS FILED HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA		RATE	FEE
Total Claims	6	MINUS 20	= 0	×	\$ 50	= \$ 0
Independent Claims	1	MINUS 3	= 0	×	\$ 210	= \$ 0
<input type="checkbox"/> [ 1/2/3 ] month(s) extension of time is hereby requested.						= \$ 0
<input type="checkbox"/> Terminal Disclaimer Fee						= \$ 0
<input type="checkbox"/> Fee regarding Submission of an Information Disclosure Statement .						= \$ 0
Total:						= \$ 0

RECEIVED  
CENTRAL FAX CENTER

MAR 13 2008

Patent

Customer No. 31561  
Docket No. 10544-US-PA  
Application No.: 10/709,179

If the payment is not fully covered in response thereof, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No.: 50-2620 (Order No.:10544-US-PA).

Thank you for your attention and assistance in this matter. If you have any questions, please feel free to contact the undersigned.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date: March 13, 2008

By: Belinda Lee  
Belinda Lee  
Registration No.: 46,863

Please send future correspondence to:  
7F. -1, No. 100, Roosevelt Rd.,  
Sec. 2, Taipei 100, Taiwan, R.O.C.  
Tel: 886-2-2369 2800 Fax: 886-2-2369 7233 / 886-2-2369 7234  
E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw

MAR 13 2008

Customer No.: 31561  
Application No.: 10/709,179  
Docket No.: 10544-US-PA

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: Ha, Nathan W.

Group Art Unit: 2814

In re PATENT APPLICATION of

Applicants : Chang et al.

Serial No. : 10/709,179

Filed : April 19, 2004

For : STACK-TYPE MULTI-CHIP  
PACKAGE AND METHOD OF  
FABRICATING BUMPS ON  
THE BACKSIDE OF A CHIPAMENDMENTS) Attorney Docket: 10544-US-PA  
)

No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10544-US-PA)

AMENDMENTS AND RESPONSE TO OFFICE ACTION

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The Office Action dated December 13, 2007, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.